Advanced IC Packaging Technologies, Materials and Markets, 2016 Edition

Description:
The demand for consumer electronics and mobile communications devices that keep us connected is driving electronics manufacturers to deliver ever-more compact and portable products. Today's users ask for solutions that deliver more functionality, added performance, higher speed, and smaller form factors. Software systems and billions of networked devices are rapidly coalescing into a vast Internet of Things.

All of these forces are driving semiconductor companies to develop new advanced IC packaging technologies to provide greater silicon integration in increasingly miniaturized packages. The last decade has seen an explosion of new products including fan-out wafer-level packaging (FOWLPs), stacked IC packages and complex system-in-packages (SiPs), as well as advances in package substrates, flip chip interconnection and through silicon vias.

All these advances are enabling significant improvements in packaging density and opening new market opportunities for manufacturers. This latest report reveals the latest technology and market trends in the IC packaging industry by focusing on the most advanced packaging products and solutions—those critical to success in developing cutting-edge products and in maintaining technological leadership. Every market or application segment discussed in the report includes quantitative analysis based on the most current historical years, 2014 and 2015, as well as forecasts from 2016 through 2020. Each of the eight chapters covers a different topic and market segment.

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